ABSTRACT

An information carrier in which an IC element formed integrally with a coil is mounted and which has an extended communication range and a method of manufacturing the same and a structure of the IC element appropriately suited for this sort of information carrier and a method of manufacturing the same. In the IC element, a conductor constituting the coil 3 is implemented in a multilayer structure including a metal-sputtered layer or alternatively a metal-evaporated layer 6 and a metal-plated layer 7. In the method of manufacturing the IC element, a precision electroforming method is employed as a means for forming the metal-plated layer 7. The information carrier is implemented in such a structure in which the IC element 1 is disposed at a center portion in a planar direction of a substrate 21. In a method of manufacturing the information carrier, strip material or materials 41 to 45 a given one of which has mounted thereon desired parts inclusive of the IC elements are manufactured, whereon desired information carriers 20a, ..., 20h are formed by punching the strip material(s).